FT_TGF_042_AB_NS_63

Thermal Pad

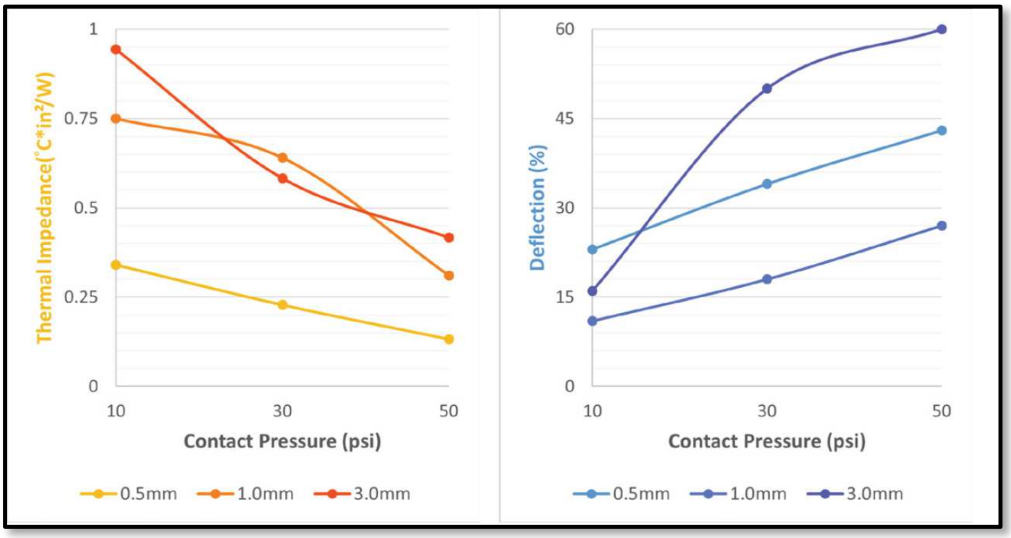
Our Thermal Foam also called Gap Pad or Gap Filler are silicone-free thermo-conductive materials that solve the heat dissipation problems. The TGF_042_NS is a mattress specially developed for applications where a medium cooling need is required. Indeed, it is a good thermal conductor of 4.2W/mK, with good thermal resistance thus facilitating the transfer of heat and also has excellent electrical insulation. Below 1mm, the mattress is hardly usable in pick-in-place for robotic production, in this case it will be necessary to adjust its hardness before use. We can cut out according to customer plan.

Application areas: Electronic components - Electric vehicles, 5G, Automatic driving system, Mobile phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, Motherboard, Power supply, Heat sink, LCD-TV, laptop, PC, telecom device, wireless hub, DDR ll module, etc.

Technical characteristics

Features	TGF_042_NS	Unit	Tolerance	Test Method
Color	Red	-	-	Colorimètre CIE 1976
Density	2.5	g/cc	+/- 0.2	ASTM D792
Thickness	0.5-5	mm	-	ASTM D374
Hardness	50	shore 00	+/- 10	ASTM D2240
Sizes	310*310	mm	-	-
Thermal conductivity	4.2	W/mK	+/- 10%	ASTM D5470 Modified
Weight loss	< 1	%	-	ASTM E595 Modified
Elongation	100	%	-	ASTM D412
Breakdown voltage	≥ 10.2	kV/mm	-	ASTM D149
Volume resistance	> 10^{10}	Ohm-m	-	ASTM D257
UL certification	V-0	-	-	UL 94
Temperature	-30 to 125	°C	-	-

The TGF_042_NS is available in 0.5 to 5mm thicknesses.



The results were obtained under laboratory conditions and should be considered only as an indication. As AB2E has no control over its customers' equipment and many other factors, it is the user's responsibility to carry out its own tests to ensure that the product corresponds to its needs.

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